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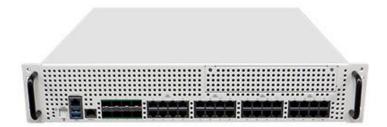
Connectivity Solutions

uCPE Large

Intel® Xeon™ D-1500 and Broadcom® Hurricane3 based uCPE

Product Description

Silicom's uCPE based on the Intel® Xeon[™] D-1500 and Broadcom® Hurricane3 product line is a highly flexible network edge device that brings the agility of modular LAN, WAN, management, and compute to cost-sensitive applications in SD-WAN, CPE, Security, Small Cell, MEC, vRAN, Cell Site, Cloud Edge, Aggregation Router and IoT.



With a new type of modularity x86 and networking switch engine designed specifically for networking application. Silicom uCPE is the ideal platform upon which to deploy next-generation edge applications

Technical Specifications

General Technical Specifications		
CPU:	Intel® Xeon™ D-1577 16 Cores, 32 threads Base Freq. 1.3GHz, 24MB Cache, TDP 45W Platfrom will also support Xeon-D NS SKU's	
BIOS:	UEFI BIOS	
BIOS Flash:	SPI	
Switch Chips set:	Broadcom® Hurricane3 BCM56172	
Copper PHY:	Broadcom® 1G Phy BCM54292 / BCM50292 or compatible	
Memory:	64GB DDR4 with ECC 4x 16GB DIMMs DDDR4 with ECC	
Storage:	1x 64GB eMMC 2x 3TB 2.5"/3.5" HD	
Internal Switch:	2x 10GE-KR Optional additional 2x10GE-KR with NS SKU	

External Switch Ports:	32x 1GE RJ45 8x SFP+ 32 of 32 supports (POE+) *Total Power limit of the 32 POE + Up to 800W Dynamic power load based on actual power consumption	
Host Mgmt:	1GbE RJ45 on Management Card, Shared with BMC. 1GbE Between BMC and Switch	
USB 3.0:	2xFront, 2x Internal Vertical	
Serial Console:	RJ45 connector using RS232 signaling	
LTE:	M.2 Key-B, support 3042 Card. Externally accessible SIM card supported. Mini PCIe supporting USB2.0/3.0 and externally accessible SIM card.	
WiFi:	No support for WiFi	
M.2 Expansion:	1xM.2 Key B with support up to 30x110mm	
BMC:	μBMC	
TPM:	TPM 2.0	
Power:	Dual redundant w/ Dying Gasp AC in, 1200W / 54.5VDC out	
LED's:	Management card support three tri-color configurable LED's (red, green, blue)	
Other Hardware:	Configurable Recessed button (Recommend for Factory reset) Configurable Large button (Recommend for power)	
Form Factor:	2U rackmount Form Factor EIA 19" (WxDxH) = 430 x 474 x 88mm	
Expansion / Voice Module:	PCIe x16: Support for either Voice module or 2/ M4 module. Support for Voice module is connected directly to the CPU board. In order to support M4 module, needs to install mid plan expansion kit. Mid plan kit in not part of BOM.	
Weight:	12.4kg (437.4oz)	
Power Consumption:	Maximum: 100-120Vac 50-60Hz 15A / 200-240Vac 50-60Hz 8A Typical: 100-120Vac 50-60Hz 10A / 200-240Vac 50-60Hz 5A The total power consumption of the card depends on user application	
Cooling:	FANs, Number of Fans TBD, Design supports 3 FAN front-to-back airflow	
Sensors/Monitors:	Thermal protection Critical Error Detection Voltage monitors Current protection	
Operating Temperature:	0°C – 40°C (32°F – 104°F)	
Storage:	-40°C–65°C (-40°F–149°F)	

Operating Altitude:	10000 ft (3048 m)	
Regulation:	CE, FCC Class A, ROHS requirements	
MTBF*:	76344 hours * According to Telcordia SR-332 Issue 4. Environmental condition – GB (Ground, Fixed, and Controlled). Ambient temperature 40°C	

Order Information

P/N	Description	Notes
80500-0181-G10	uCPE , 2U,19",D1577(16C),DDR4/64GB/ECC,2xPS	